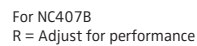




| | |
|-----------------------|--|
| Frequency | 100 MHz to 110 GHz |
| V_b | 8 to 12V |
| I_{op} | 8mA |
| R_L | 50 ohms |
| ENR output | 15 – 25dB |
| Package | B |
| I_{max} | 10mA |
| Output | White Gaussian |
| Operating Temperature | -55°C to +125°C |
| Storage Temperature | -65°C to +150°C |
| Shipping Package | Gel Pack |
| Assembly | Silver expoxy is recommended, however Gap welding or thermo compression can be used. |

Technical drawing of a B Package (inches) showing dimensions for a glass-to-silicon assembly. The drawing includes a cross-section of a glass component with a central cavity, mounted on a silicon substrate. Dimensions are given in inches: .008, .010, .005, .008, .029, .003, and .015. Labels include 'GLASS', 'SILICON', and 'B Package (inches)'.



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